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HEET

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3-1-99  
Yongjun Jeff Hu  
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2. Name and address of receiving party(ies):  
Name: Micron Technology, Inc.  
Internal Address:  
Street Address: 8000 South Federal Way  
City: Boise State: ID Zip: 83706  
Additional names(s) & address(es) attached:  Yes  No

3. Nature of conveyance:  
 Assignment  Security Agreement  
 Merger  Change of Name  
 Other  
Execution Date: 2/22/99

4. Application number(s) or patent number(s): 09/260,237  
If this document is being filed together with a new application, the execution date of the application is: Feb. 22, 1999  
A. Patent Application No.(s):  
Additional numbers attached:  Yes  No

B. Patent No.(s):  
Additional numbers attached:  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:  
Name: Mark S. Matkin  
Internal Address: Wells, St. John, Roberts,  
Gregory & Matkin P.S.  
Street Address: 601 W. First Avenue, Ste. 1300  
City: Spokane State: WA Zip: 99201-3828  
FL: 08

6. Total number of applications and patents involved. 1  
7. Total fee (37 CFR 3.41). \$ 40  
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*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*  
Mark S. Matkin,  
Name of Person Signing [Signature] Signature 3/1/99 Date  
TOTAL NUMBER OF PAGES INCLUDING COVER SHEET, ATTACHMENTS AND DOCUMENT: 5

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PATENT ASSIGNMENTPARTIES TO THE ASSIGNMENT:INVENTOR:

Yongjun Jeff Hu

ASSIGNEE:

Micron Technology, Inc.  
Corporation of the State of Delaware  
8000 South Federal Way  
Boise, Idaho 83706-9632

BACKGROUND OF THIS ASSIGNMENT:

INVENTOR has conceived certain new and useful inventions disclosed in a United States patent application titled **Method Of Depositing A Nitrogen Enriched Metal Layer, Method Of Forming A Silicide Contact To A Silicon Comprising Substrate, Method Of Forming A Metal Source Layer In An Integrated Circuit, Method Of Analyzing Impact Of Operating Parameter Changes For A Plasma Deposition Reactor Having An Inductive Coil Positioned Therein, Method Of Forming Integrated Circuitry.**

MICRON TECHNOLOGY, INC. desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

**THE PARTIES AGREE AS FOLLOWS:**

In consideration of good and valuable consideration, the receipt sufficiency and adequacy of which is hereby acknowledged, INVENTOR hereby sells, assigns and transfers to MICRON TECHNOLOGY, INC. the entire right and interest in the above-identified application executed concurrently with this assignment and to any reissues, renewals, divisions or continuations thereof, and hereby authorizes the Commissioner of Patents and Trademarks to issue such Letters Patent to MICRON TECHNOLOGY, INC. for the sole use of MICRON TECHNOLOGY, INC., its successors or assigns.

INVENTOR further agrees to execute, at the request and expense of MICRON TECHNOLOGY, INC. such other formal documents as may be required to fully convey the interest transferred herein and will similarly execute any application papers required for the filing of any division, continuation, renewal or reissue of the patent application or resulting Letters Patent; and will generally do everything necessary or desirable to obtain and enforce proper protection for the invention assigned hereby.

INVENTOR further assigns to MICRON TECHNOLOGY, INC. the whole right, title and interest in the inventions disclosed in the application throughout all countries foreign to the United States. MICRON TECHNOLOGY, INC. is hereby authorized to apply for patents relating to the inventions in its own name in countries where such procedure is proper; to claim the benefit of the International

1 Convention; to file and prosecute International Applications relating to  
2 the inventions under the Patent Cooperation Treaty; and to file and  
3 prosecute applications relating to the inventions under the European  
4 Patent Convention. INVENTOR agrees to execute applications relating  
5 to the inventions in those countries and under those conventions where  
6 it is necessary that the same be executed by the inventor, and to  
7 execute assignments of such applications and the resulting Letters Patent  
8 to MICRON TECHNOLOGY, INC. as well as all other necessary papers  
9 in relation to such applications and Letters Patent.

10 INVENTOR further warrants and covenants that no assignment,  
11 grant, mortgage, license or other agreement affecting the rights and  
12 property herein conveyed has been or will be made to others by the  
13 undersigned, and that the full rights to convey the same as herein  
14 expressed is possessed by the undersigned.

15 To be binding on the heirs, assigns, representatives and successors  
16 of the undersigned and extend to the successors, assigns and nominees  
17 of the Assignees.

1 (Signature)

Yongjun Jeff Hu

Date:

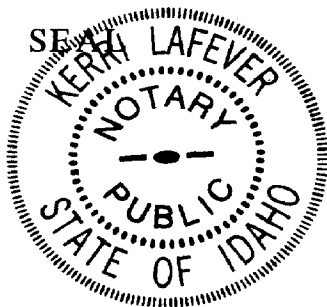
Feb 22, 1999

2  
3 State of Idaho )

) ss.

4 County of Ada )

5 BEFORE ME, this 22 day of February 1999  
6 personally appeared the above-named inventor, to me known to be the  
7 person who is described in and who executed the foregoing assignment  
instrument and acknowledged to me that he/she executed the same of  
his/her own free will for the purpose therein expressed.



8  
9  
10 Kerry Lavever  
11 Notary or Consular Officer  
12 My Commission Expires: 1/9/2002